



## **PRESS RELEASE**

Contact: Jan Vardaman  
(512) 372-8887

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### **Miniaturization Trends Drive Growth in SiP Market**

With the proliferation of mobile electronic products and the ongoing push for greater functionality in a smaller area, miniaturization has become a key word for system-in-package (SiP). SiP provides increased functionality in a subsystem that can be more cost-effectively assembled into a system. Miniaturization and other technology trends driving SiP market growth are covered in TechSearch International's new study, **SiP for Mobile and Wearable Applications: Market Forecasts and the Changing Business Model**. The thorough analysis is based on the company's 28-year history of studying markets and critical technology and infrastructure issues.

In many cases SiP provides lower cost and quicker time to market than a system-on-chip (SoC) approach. In today's world of mobile product introductions that must ramp in four to five months and may only have a lifetime of a year, SiP is essential to the success of new products in this space.

SiPs are found in many products including smartphones, tablets, wearable electronics (including medical products), and other consumer products. High-performance gaming systems, computers, and network systems also use SiP, as do automotive electronics. Future applications may include IoT-related areas such as smart homes, energy products, and industrial automation.

SiP is defined as two or more dissimilar die, typically combined with other components such as passives, filters, MEMS, sensors, and antennas, assembled into a standard footprint package to create a functional system or subsystem. Characteristics of SiPs vary widely and the major attributes can differ depending on the application. In the wireless market, integration, form factor, cost, and shielding are the top interests. For wearable electronics, the drivers are low power, cost, miniaturization, and high yield assembly. In some cases, very highly integrated solutions are needed. Drivers for these include low cost, greater performance, low power, and easy design-in where there is a low entry barrier, with short time-to-market being a critical factor. Automotive SiP features include high power capability, reliability, testability, and form factor. For power modules, the drivers are power efficiency, miniaturization, and EMI shielding.

The 76-page report with full references provides forecasts for the SiP market in units by application and package type. Key requirements for SiP are examined and the roles of design, EMI shielding, and known good die are discussed. The capabilities of OSATs and EMS players are covered. Companies providing SiP assembly services are listed. A set of 49 PowerPoint slides accompanies the report.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 17,000 contacts in North America, Asia, and Europe. For more information, call TechSearch at 512-372-8887 or see [www.techsearchinc.com](http://www.techsearchinc.com).